

#### **Features**

- 25-W/ch into an 4 Ω Loads at 10% THD+N From a 16-V Supply
- 10-W/ch into 8-Ω Loads at 10% THD+N From a 13-V Supply

90% Efficient Class-D Operation Eliminates

- Wide Supply Voltage Range Allows Operation from 8 V to 26 V
- Filter-Free Operation

Need for Heat Sinks

- Speaker Protection Includes Adjustable Power Limiter plus DC Protection
- Flow Through Pin Out Facilitates Easy Board Layout
- Robust Pin-to-Pin Short Circuit Protection and Thermal Protection with Auto Recovery Option
- · Excellent THD+N / Pop-Free Performance
- · Four Selectable, Fixed Gain Settings
- Differential Inputs

#### **Description**

The AT3110C is a 15-W (per channel) efficient, Class-D audio power amplifier for driving bridged-tied stereo speakers. Advanced EMI Suppression Technology enables the use of inexpensive ferrite bead filters at the outputs while meeting EMC requirements. Speaker protection circuitry includes an adjustable power limiter and a DC detection circuit. The adjustable power limiter allows the user to set a "virtual" voltage rail lower than the chip supply to limit the amount of current through the speaker. The DC detect circuit measures the frequency and amplitude of the PWM signal and shuts off the output stage if the input capacitors are damaged or shorts exist on the inputs.

The AT3110C can drive stereo speakers as low as 4  $\Omega$ . The high efficiency of the AT3110C, 90%, eliminates the need for an external heat sink when playing music.

The outputs are also fully protected against shorts to GND, VCC, and output-to-output. The short-circuit protection and thermal protection includes an autorecovery feature.

#### **Applications**

- · Televisions
- · Consumer Audio Equipment

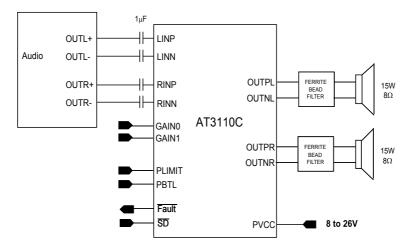
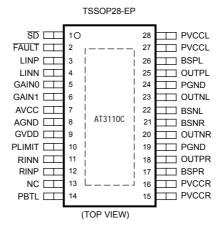


Figure 1. AT3110C Simplified Application Schematic

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## **Pin Configuration**

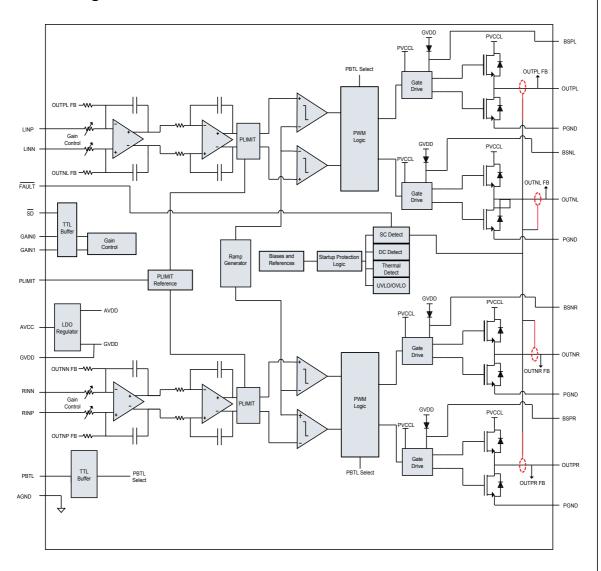


## **Pin Descriptions**

PIN		1/O/D	DECODIDATION	
NAME NUMBER		I/O/P	DESCRIPTION	
SD	1	I	Shutdown logic input for audio amp (LOW = outputs Hi-Z, HIGH = outputs enabled). TTL logic levels with compliance to AVCC.	
FAULT	2	0	Open drain output used to display short circuit or dc detect fault status. Voltage compliant to AVCC. Short circuit faults can be set to auto-recovery by connecting FAULT pin to SD pin. Otherwise, both short circuit faults and dc detect faults must be reset by cycling PVCC.	
LINP	3	1	Positive audio input for left channel. Biased at 3V.	
LINN	4	l	Negative audio input for left channel. Biased at 3V.	
GAIN0	5	1	Gain select least significant bit. TTL logic levels with compliance to AVCC.	
GAIN1	6	1	Gain select most significant bit. TTL logic levels with compliance to AVCC.	
AVCC	7	Р	Analog supply	
AGND	8		Analog signal ground. Connect to the thermal pad.	
GVDD	9	0	High-side FET gate drive supply. Nominal voltage is 7V. Also should be used as supply for PLIMIT function	
PLIMIT	10	I	Power limit level adjust. Connect a resistor divider from GVDD to GND to set power limit. Connect directly to GVDD for no power limit.	
RINN	11	I	Negative audio input for right channel. Biased at 3V.	
RINP	12	Į.	Positive audio input for right channel. Biased at 3V.	
NC	13		Not connected	
PBTL	14	I	Parallel BTL mode switch	
PVCCR	15	Р	Power supply for right channel H-bridge. Right channel and left channel power supply inputs are connect internally.	
PVCCR	16	Р	Power supply for right channel H-bridge. Right channel and left channel power supply inputs are connect internally.	
BSPR	17	I	Bootstrap I/O for right channel, positive high-side FET.	
OUTPR	18	0	Class-D H-bridge positive output for right channel.	
PGND	19		Power ground for the H-bridges.	
OUTNR	20	0	Class-D H-bridge negative output for right channel.	
BSNR	21	I	Bootstrap I/O for right channel, negative high-side FET.	
BSNL	22	I	Bootstrap I/O for left channel, negative high-side FET.	
OUTNL	23	0	Class-D H-bridge negative output for left channel.	
PGND	24		Power ground for the H-bridges.	
OUTPL	25	0	Class-D H-bridge positive output for left channel.	
BSPL	26	I	Bootstrap I/O for left channel, positive high-side FET.	
PVCCL	27	Р	Power supply for left channel H-bridge. Right channel and left channel power supply inputs are connect internally.	
PVCCL	28	Р	Power supply for left channel H-bridge. Right channel and left channel power supply inputs are connect internally.	



## **Block Diagram**





## **Typical Application**

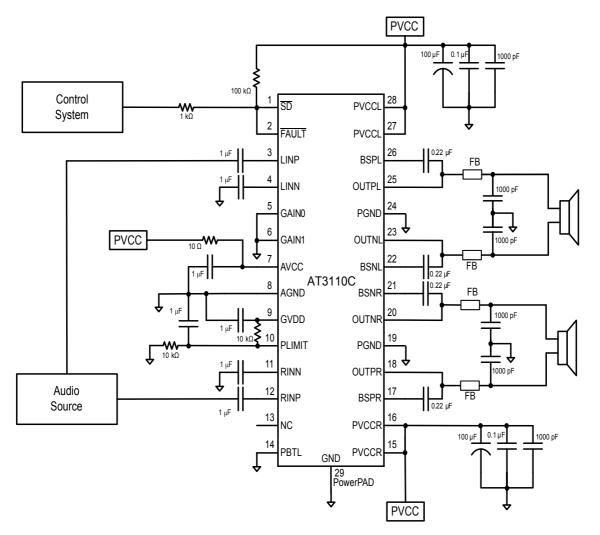
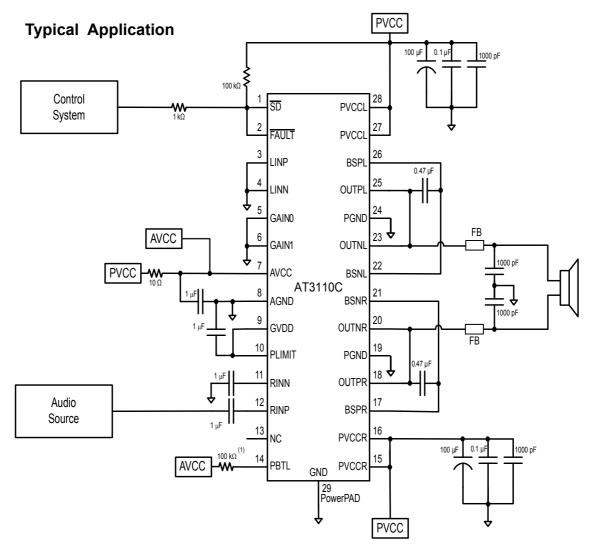


Figure 2. Stereo Class-D Amplifier with BTL Output and Single-Ended Inputs with Power Limiting

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(1) 100  $k\Omega$  resistor is needed if the PVCC slew rate is more than 10 V/ms.

Figure 3. Stereo Class-D Amplifier with PBTL Output and Single-Ended Input



## **Absolute Maximum Ratings**

over operating free-air temperature range (unless otherwise noted)(1)

			UNIT	
V <sub>CC</sub>	Supply voltage	AVCC, PVCC	–0.3 V to 30 V	
		SD, GAINO, GAIN1, PBTL, FAULT (2)	-0.3 V to V <sub>CC</sub> + 0.3 V	
V	Interface nin voltage	SD, GAINU, GAINT, PBTL, FAULT	< 10 V/ms	
V <sub>I</sub>	Interface pin voltage	PLIMIT	-0.3 V to GVDD + 0.3 V	
		RINN, RINP, LINN, LINP	–0.3 V to 6.3 V	
	Continuous total power dissipation		See the Thermal Information Table	
T <sub>A</sub>	Operating free-air temperature range		-40°C to 85°C	
TJ	Operating junction tempera	ture range <sup>(3)</sup>	-40°C to 150°C	
T <sub>stg</sub>	Storage temperature range		−65°C to 150°C	
		BTL: PVCC > 15 V	4.8	
$R_L$	Minimum Load Resistance	BTL: PVCC ≤ 15 V	3.2	
		PBTL	3.2	
COD	Clastrostatia diasharea	Human body model (4) (all pins)	±2 kV	
ESD	Electrostatic discharge	Charged-device model <sup>(5)</sup> (all pins)	±500 V	

- (1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operations of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The voltage slew rate of these pins must be restricted to no more than 10 V/ms. For higher slew rates, use a 100 kΩ resister in series with the pins.
- (3) The AT3110C incorporates an exposed thermal pad on the underside of the chip. This acts as a heatsink, and it must be connected to a thermally dissipating plane for proper power dissipation. Failure to do so may result in the device going into thermal protection shutdown.
- (4) In accordance with JEDEC Standard 22, Test Method A114-B.
- (5) In accordance with JEDEC Standard 22, Test Method C101-A

### Thermal Information

	THERMAL METRIC		LINITO
			UNITS
$\theta_{JA}$	Junction-to-ambient thermal resistance	30.3	
$\theta_{\text{JCtop}}$	JCtop Junction-to-case (top) thermal resistance		
$\theta_{JB}$	P <sub>JB</sub> Junction-to-board thermal resistance		°C/W
ΨЈТ	Junction-to-top characterization parameter	0.9	C/VV
ΨЈВ	Junction-to-board characterization parameter		
$\theta_{\text{JCbot}}$	Junction-to-case (bottom) thermal resistance	0.9	

## **Ordering and Marking Information**

Device	Package Type	Device Marking	Reel Size	Tape Width	Quantity
AT3110C	TSSOP28-EP	AT3110C .XXX	13"	16	3000



### **Recommended Operating Conditions**

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MAX	UNIT
V <sub>CC</sub>	Supply voltage	PVCC, AVCC	8	26	V
V <sub>IH</sub>	High-level input voltage	SD, GAIN0, GAIN1, PBTL	2		V
V <sub>IL</sub>	Low-level input voltage	SD, GAIN0, GAIN1, PBTL		0.8	V
V <sub>OL</sub>	Low-level output voltage	FAULT, R <sub>PULL-UP</sub> =100k, V <sub>CC</sub> =26V		0.8	V
I <sub>IH</sub>	High-level input current	SD, GAIN0, GAIN1, PBTL, V <sub>I</sub> = 2V, V <sub>CC</sub> = 18 V		50	μA
I <sub>IL</sub>	Low-level input current	SD, GAINO, GAIN1, PBTL, V <sub>I</sub> = 0.8 V, V <sub>CC</sub> = 18 V		5	μA
T <sub>A</sub>	Operating free-air temperature		-40	85	°C

### **DC Characteristics**

 $T_A = 25^{\circ}C$ ,  $V_{CC} = 24 \text{ V}$ ,  $R_L = 8 \Omega$  (unless otherwise noted)

	PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT	
Vos	Class-D output offset voltage (measured differentially)	V <sub>I</sub> = 0 V, Gain = 36 dB			1.5	15	mV
Icc	Quiescent supply current	SD = 2 V, no load, PV <sub>CC</sub> = 24V	1		32	50	mA
I <sub>CC(SD)</sub>	Quiescent supply current in shutdown mode	$\overline{SD}$ = 0.8 V, no load, PV <sub>CC</sub> = 24	4V		250	400	μΑ
_	Drain course on etate registence	V <sub>CC</sub> = 12 V, I <sub>O</sub> = 500 mA,	High Side		240		m0
r <sub>DS(on)</sub>	Drain-source on-state resistance	T <sub>J</sub> = 25°C	Low side		240		mΩ
		GAIN1 = 0.8 V	GAIN0 = 0.8 V	19	20	21	dB
0			GAIN0 = 2 V	25	26	27	uв
G	Gain	GAIN1 = 2 V	GAIN0 = 0.8 V	31	32	33	4D
			GAIN0 = 2 V	35	36	37	dB
t <sub>on</sub>	Turn-on time	<del>SD</del> = 2 V			14		ms
t <sub>OFF</sub>	Turn-off time	<del>SD</del> = 0.8 V			2		μs
GVDD	Gate Drive Supply	I <sub>GVDD</sub> = 100μA		6.4	6.9	7.4	V
t <sub>DCDET</sub>	DC Detect time	V <sub>(RINN)</sub> = 6V, VRINP = 0V			420		ms

### **DC Characteristics**

 $T_A$  = 25°C,  $V_{CC}$  = 12 V,  $R_L$  = 8  $\Omega$  (unless otherwise noted)

	PARAMETER	TEST CONDITIO	NS	MIN	TYP	MAX	UNIT
Vos	Class-D output offset voltage (measured differentially)	V <sub>I</sub> = 0 V, Gain = 36 dB			1.5	15	mV
I <sub>CC</sub>	Quiescent supply current	SD = 2 V, no load, PV <sub>CC</sub> = 12V			20	35	mA
I <sub>CC(SD)</sub>	Quiescent supply current in shutdown mode	$\overline{SD}$ = 0.8 V, no load, PV <sub>CC</sub> = 12	?V		200		μΑ
_	Designation of the second	V <sub>CC</sub> = 12 V, I <sub>O</sub> = 500 mA,	High Side		240		0
r <sub>DS(on)</sub>	Drain-source on-state resistance	T <sub>J</sub> = 25°C	Low side		240		mΩ
		0.4114 0.034	GAIN0 = 0.8 V	19	20	21	-ID
0	Out	GAIN1 = 0.8 V	GAIN0 = 2 V	25	26	27	dB
G	Gain	GAIN1 = 2 V	GAIN0 = 0.8 V	31	32	33	-ID
			GAIN0 = 2 V	35	36	37	dB
t <sub>ON</sub>	Turn-on time	SD = 2 V			14		ms
t <sub>OFF</sub>	Turn-off time	<del>SD</del> = 0.8 V			2		μs
GVDD	Gate Drive Supply	I <sub>GVDD</sub> = 2mA		6.4	6.9	7.4	V
V <sub>O</sub>	Output Voltage maximum under PLIMIT control	V <sub>(PLIMIT)</sub> = 2 V; V <sub>I</sub> = 1V rms		6.75	7.90	8.75	V



### **AC Characteristics**

 $T_{\Delta}$  = 25°C,  $V_{CC}$  = 24 V,  $R_{I}$  = 8  $\Omega$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
K <sub>SVR</sub>	Power Supply ripple rejection	200 mV <sub>PP</sub> ripple at 1 kHz, Gain = 20 dB, Inputs ac-coupled to AGND		-70		dB
Po	Continuous output power	THD+N = 10%, f = 1 kHz, V <sub>CC</sub> = 16 V		15		W
THD+N	Total harmonic distortion + noise	V <sub>CC</sub> = 16 V, f = 1 kHz, P <sub>O</sub> = 7.5 W (half-power)		0.1		%
V Output integrated paigs		20 Hz to 22 kHz, A-weighted filter, Gain = 20 dB		65		μV
V <sub>n</sub> Output integrated noise	20 HZ to 22 kHZ, A-weighted litter, Gairi – 20 db		-80		dBV	
	Crosstalk	V <sub>O</sub> = 1 Vrms, Gain = 20 dB, f = 1 kHz		-100		dB
SNR	Signal-to-noise ratio	Maximum output at THD+N < 1%, f = 1 kHz, Gain = 20 dB, A-weighted		102		dB
f <sub>OSC</sub>	Oscillator frequency		250	310	350	kHz
	Thermal trip point			150		°C
	Thermal hysteresis			15		°C

#### **AC Characteristics**

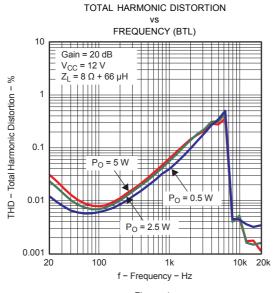
 $T_{A}$  = 25°C,  $V_{CC}$  = 12 V,  $R_{L}$  = 8  $\Omega$  (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
K <sub>SVR</sub>	Supply ripple rejection	200 mV <sub>PP</sub> ripple from 20 Hz–1 kHz, Gain = 20 dB, Inputs ac-coupled to AGND		-70		dB
Po	Continuous output power	THD+N = 10%, f = 1 kHz; V <sub>CC</sub> = 13 V		10		W
THD+N	Total harmonic distortion + noise	$R_L = 8 \Omega$ , $f = 1 \text{ kHz}$ , $P_O = 5 \text{ W}$ (half-power)		0.06		%
V	Output integrated pains	20 He to 22 kHe A weighted filter Coin = 20 dD		65		μV
V <sub>n</sub> Output integrated noise	Output integrated noise	20 Hz to 22 kHz, A-weighted filter, Gain = 20 dB		-80		dBV
	Crosstalk	P <sub>o</sub> = 1 W, Gain = 20 dB, f = 1 kHz		-100		dB
SNR	Signal-to-noise ratio	Maximum output at THD+N < 1%, f = 1 kHz, Gain = 20 dB, A-weighted		102		dB
fosc	Oscillator frequency		250	310	350	kHz
	Thermal trip point			150		°C
	Thermal hysteresis			15		°C

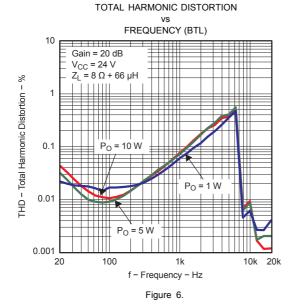


#### **Typical Operating Characteristics**

(All Measurements taken at 1 kHz, unless otherwise noted.)







## TOTAL HARMONIC DISTORTION

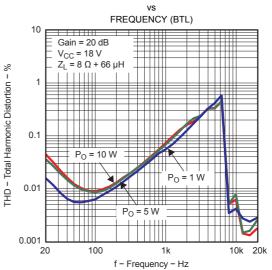


Figure 5.

#### TOTAL HARMONIC DISTORTION

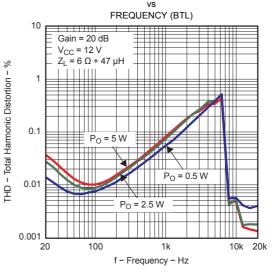


Figure 7.



### **Typical Operating Characteristics**

(All Measurements taken at 1 kHz, unless otherwise noted.)

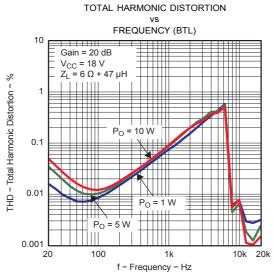


Figure 8.

TOTAL HARMONIC DISTORTION + NOISE

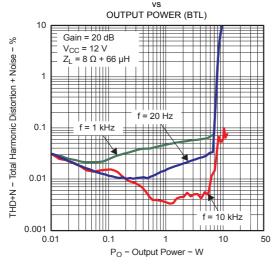


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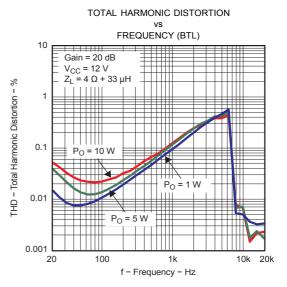


Figure 9.

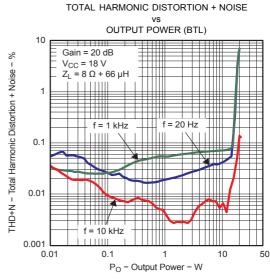


Figure 11.



### **Typical Operating Characteristics**

(All Measurements taken at 1 kHz, unless otherwise noted.)

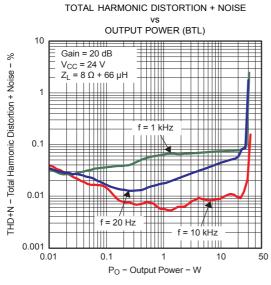
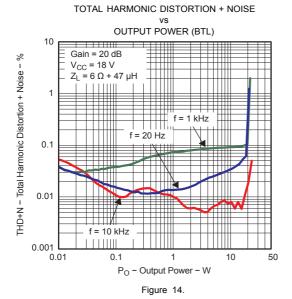
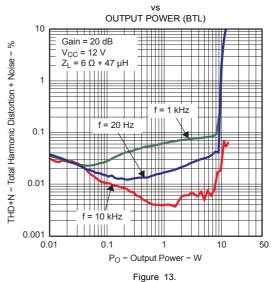


Figure 12.



TOTAL HARMONIC DISTORTION + NOISE



TOTAL HARMONIC DISTORTION + NOISE vs

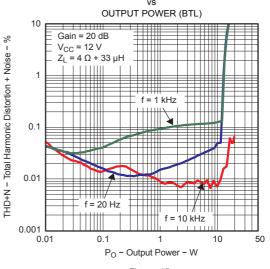
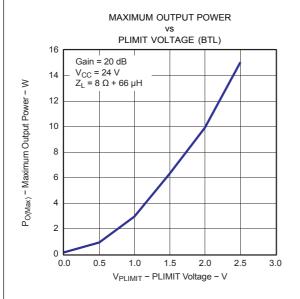


Figure 15.



### **Typical Operating Characteristics**

(All Measurements taken at 1 kHz, unless otherwise noted.)



PLIMIT VOLTAGE (BTL)

35

Gain = 20 dB

V<sub>CC</sub> = 12 V

Z<sub>L</sub> = 4 Ω + 33 μH

25

20

10

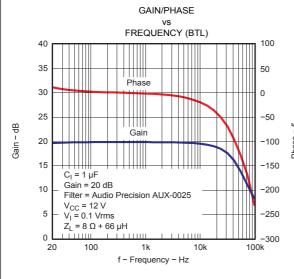
5

V<sub>PLIMIT</sub> - PLIMIT Voltage - V

**OUTPUT POWER** 

Figure 16.

Note: Dashed Lines represent thermally limited regions. Figure 17.



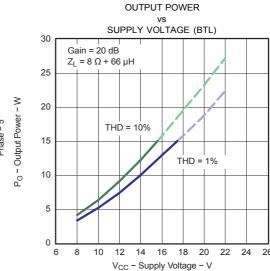


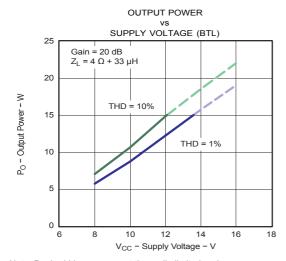
Figure 18.

Note: Dashed Lines represent thermally limited regions. Figure 19.



### **Typical Operating Characteristics**

(All Measurements taken at 1 kHz, unless otherwise noted.)



Note: Dashed Lines represent thermally limited regions. Figure 20.

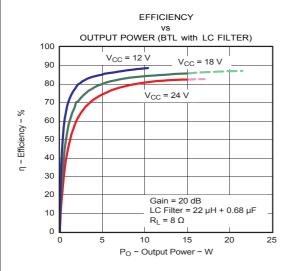
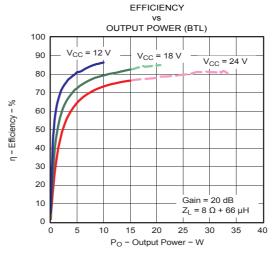
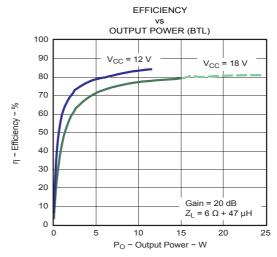


Figure 22.



Note: Dashed Lines represent thermally limited regions. Figure 21.



Note: Dashed Lines represent thermally limited regions. Figure 23.



### **Typical Operating Characteristics**

(All Measurements taken at 1 kHz, unless otherwise noted.)

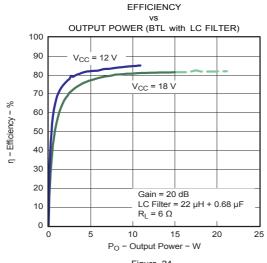


Figure 24.

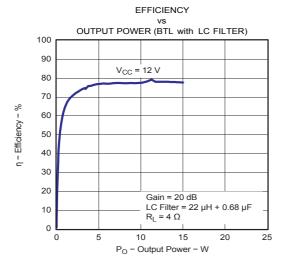
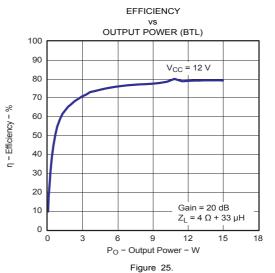
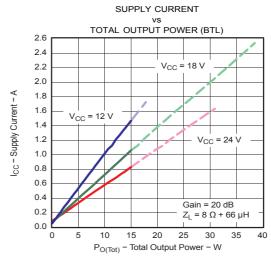


Figure 26.



. .9.... \_-..

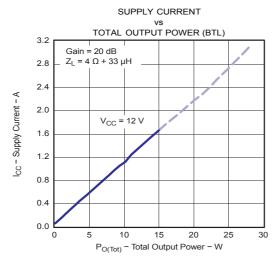


Note: Dashed Lines represent thermally limited regions. Figure 27.

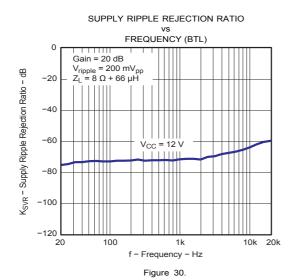


### **Typical Operating Characteristics**

(All Measurements taken at 1 kHz, unless otherwise noted.)



Note: Dashed Lines represent thermally limited regions. Figure 28.



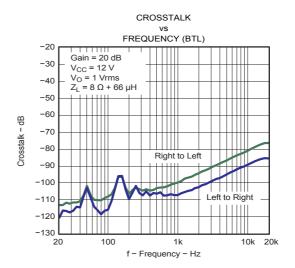
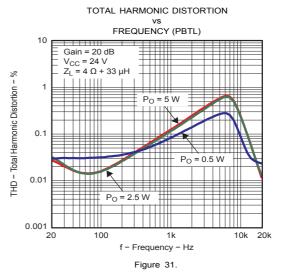


Figure 29.

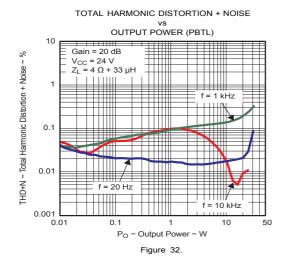


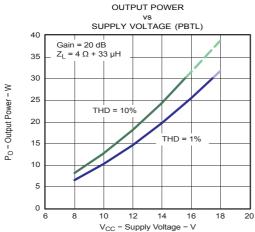
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### **Typical Operating Characteristics**

(All Measurements taken at 1 kHz, unless otherwise noted.)





Note: Dashed Lines represent thermally limited regions. Figure 34.

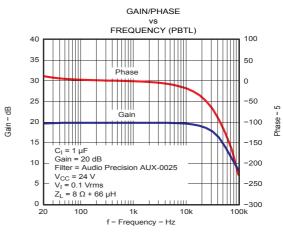


Figure 33.

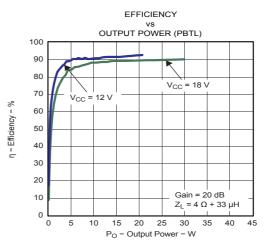
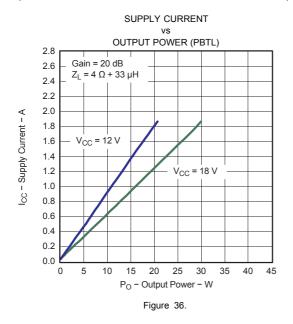


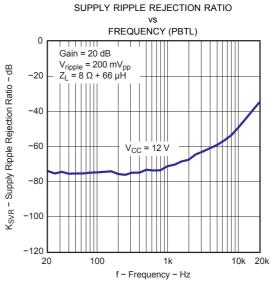
Figure 35.



### **Typical Operating Characteristics**

(All Measurements taken at 1 kHz, unless otherwise noted.)







### **Application Information**

Gain setting via GAIN0 and GAIN1 inputs

The gain of the AT3110C is set by two input terminals, GAIN0 and GAIN1. The voltage slew rate of these gain terminals, along with terminals 1 and 14, must be restricted to no more than 10V/ms. For higher slew rates, use a  $100k\Omega$  resistor in series with the terminals.

The gains listed in Table 1 are realized by changing the taps on the input resistors and feedback resistors inside the amplifier. This causes the input impedance (ZI) to be dependent on the gain setting. The actual gain settings are controlled by ratios of resistors, so the gain variation from part-to-part is small. However, the input impedance from part-to-part at the same gain may shift by ±20% due to shifts in the actual resistance of the input resistors.

For design purposes, the input network (discussed in the next section) should be designed assuming an input impedance of 7.2 k $\Omega$ , which is the absolute minimum input impedance of the AT3110C. At the lower gain settings, the input impedance could increase as high as 72 k $\Omega$ 

Table 1. Gain Setting

GAIN1	GAIN1 GAIN0		INPUT IMPEDANCE (kΩ)
		TYP	TYP
0	0	20	60
0	1	26	30
1	0	32	15
1	1	36	9

#### SD Operation

The AT3110C employs a shutdown mode of operation designed to reduce supply current (ICC) to the absolute minimum level during periods of nonuse for power conservation. The SD input terminal should be held high (see specification table for trip point) during normal operation when the amplifier is in use. Pulling SD low causes the outputs to mute and the amplifier to enter a low-current state. Never leave SD unconnected, because amplifier operation would be unpredictable.

For the best power-off pop performance, place the amplifier in the shutdown mode prior to removing the power supply voltage.

#### **PLIMIT**

The voltage at pin 10 can used to limit the power to levels below that which is possible based on the supply rail.

Add a resistor divider from GVDD to ground to set the voltage at the PLIMIT pin. An external reference may also be used if tighter tolerance is required. Also add a  $1\mu F$  capacitor from pin 10 to ground.

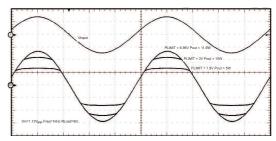


Figure 38. PLIMIT Circuit Operation

The PLIMIT circuit sets a limit on the output peak-to-peak voltage. The limiting is done by limiting the duty cycle to fixed maximum value. This limit can be thought of as a "virtual" voltage rail which is lower than the supply connected to PVCC. This "virtual" rail is 4 times the voltage at the PLIMIT pin. This output voltage can be used to calculate the maximum output power for a given maximum input voltage and speaker impedance.

$$P_{OUT} = \frac{\left(\left(\frac{R_L}{R_L + 2 \times R_S}\right) \times V_P\right)^2}{2 \times R_I}$$

for unclipped power (1)

Where:

RS is the total series resistance including RDS(on), and any resistance in the output filter. RL is the load resistance.

VP is the peak amplitude of the output possible within the supply rail.

VP = 4 × PLIMIT voltage if PLIMIT < 4 × VP POUT (10%THD) = 1.25 × POUT (unclipped)



Table 2. PLIMIT Typical Operation

		31	
Test Conditions ()	PLIMIT Voltage	Output Power (W)	Output Voltage Amplitude (V <sub>P-P</sub> )
PVCC=24V, Vin=1Vrms, RL=8Ω, Gain=26dB	6.97	36.1 (thermally limited)	43
PVCC=24V, Vin=1Vrms, RL=8Ω, Gain=26dB	2.94	15	25.2
PVCC=24V, Vin=1Vrms, RL=8Ω, Gain=26dB	2.34	10	20
PVCC=24V, Vin=1Vrms, RL=8Ω, Gain=26dB	1.62	5	14
PVCC=24V, Vin=1Vrms, RL=8Ω, Gain=20dB	6.97	12.1	27.7
PVCC=24V, Vin=1Vrms, RL=8Ω, Gain=20dB	3.00	10	23
PVCC=24V, Vin=1Vrms, RL=8Ω, Gain=20dB	1.86	5	14.8
PVCC=12V, Vin=1Vrms, RL=8Ω, Gain=20dB	6.97	10.55	23.5
PVCC=12V, Vin=1Vrms, RL=8Ω, Gain=20dB	1.76	5	15

#### **GVDD Supply**

The GVDD Supply is used to power the gates of the output full bridge transistors. It can also be used to supply the PLIMIT voltage divider circuit. Add a  $1\mu\text{F}$  capacitor to ground at this pin.

#### **DC Detect**

AT3110C has circuitry which will protect the speakers from DC current which might occur due to defective capacitors on the input or shorts on the printed circuit board at the inputs. A DC detect fault will be reported on the FAULT pin as a low state. The DC Detect fault will also cause the amplifier to shutdown by changing the state of the outputs to Hi-Z. To clear the DC Detect it is necessary to cycle the PVCC supply. Cycling S D will NOT clear a DC detect fault.

A DC Detect Fault is issued when the output differential duty-cycle of either channel exceeds 14% (for example, +57%, -43%) for more than 420 msec at the same polarity. This feature protects the speaker from large DC currents or AC currents less than 2Hz. To avoid nuisance faults due to the DC detect circuit, hold the SD pin low at power-up until the signals at the inputs are stable. Also, take care to match the impedance seen at the positive and negative inputs to avoid nuisance DC detect faults. The minimum differential input voltages required to trigger the DC detect are show in table 2. The inputs must remain at or above the voltage listed in the table for more than 420 msec to trigger the DC detect.

Table 3. DC Detect Threshold

AV(dB)	Vin (mV, differential)
20	112
26	56
32	28
36	17

#### **PBTL Select**

AT3110C offers the feature of parallel BTL operation with two outputs of each channel connected directly. If the PBTL pin (pin 14) is tied high, the positive and negative outputs of each channel (left and right) are synchronized and in phase. To operate in this PBTL (mono) mode, apply the input signal to the RIGHT input and place the speaker between the LEFT and RIGHT outputs. Connect the positive and negative output together for best efficiency. The voltage slew rate of the PBTL pin must be restricted to no more than 10V/ms. For higher slew rates, use a  $100\text{k}\Omega$  resistor in series with the terminals. For an example of the PBTL connection, see the schematic in the APPLICATION INFORMATION section

For normal BTL operation, connect the PBTL pin to local ground.

# Short-Circuit Protection And Automatic Recovery Feature

AT3110C has protection from overcurrent conditions caused by a short circuit on the output stage. The short circuit protection fault is reported on the FAULT pin as a low state. The amplifier outputs are switched to a Hi-Z state when the short circuit protection latch is engaged. The latch can be cleared by cycling the SD pin through the low state. If automatic recovery from the short circuit protection latch is desired, connect the FAULT pin directly to the SD pin. This allows the FAULT pin function to automatically drive the SD pin low which clears the short-circuit protection latch.

#### **Thermal Protection**

Thermal protection on the AT3110C prevents damage to the device when the internal die temperature exceeds  $150^{\circ}$ C. There is a  $\pm 15^{\circ}$ C tolerance on this trip point from device to device.



Once the die temperature exceeds the thermal set point, the device enters into the shutdown state and the outputs are disabled. This is not a latched fault. The thermal fault is cleared once the temperature of the die is reduced by 15°C. The device begins normal operation at this point with no external system interaction.

Thermal protection faults are NOT reported on the FAULT terminal.

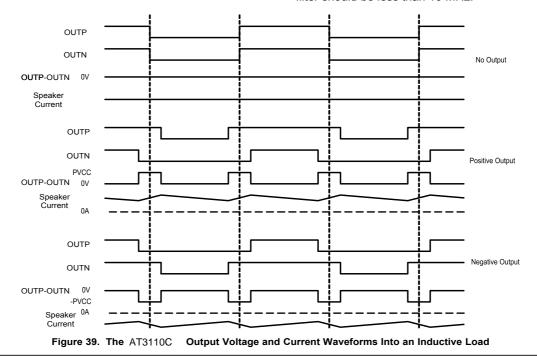
#### AT3110C Modulation Scheme

The AT3110C uses a modulation scheme that allows operation without the classic LC reconstruction filter when the amp is driving an inductive load. Each output is switching from 0 volts to the supply voltage. The OUTP and OUTN are in phase with each other with no input so that there is little or no current in the speaker. The duty cycle of OUTP is greater than 50% and OUTN is less than 50% for positive output voltages. The duty cycle of OUTP is less than 50% and OUTN is greater than 50% for negative output voltages. The voltage across the load sits at 0V throughout most of the switching period, reducing the switching current, which reduces any I2R losses in the load.

#### **Ferrite Bead Filter Considerations**

Using the Advanced Emissions Suppression Technology in the AT3110C amplifier it is possible to design a high efficiency Class-D audio amplifier while minimizing interference to surrounding circuits. It is also possible to accomplish this with only a low-cost ferrite bead filter. In this case it is necessary to carefully select the ferrite bead used in the filter.

One important aspect of the ferrite bead selection is the type of material used in the ferrite bead. Not all ferrite material is alike, so it is important to select a material that is effective in the 10 to 100 MHz range which is key to the operation of the Class D amplifier. Many of the specifications regulating consumer electronics have emissions limits as low as 30 MHz. It is important to use the ferrite bead filter to block radiation in the 30 MHz and above range from appearing on the speaker wires and the power supply lines which are good antennas for these signals. The impedance of the ferrite bead can be used along with a small capacitor with a value in the range of 1000 pF to reduce the frequency spectrum of the signal to an acceptable level. For best performance, the resonant frequency of the ferrite bead/ capacitor filter should be less than 10 MHz.





Also, it is important that the ferrite bead is large enough to maintain its impedance at the peak currents expected for the amplifier. Some ferrite bead manufacturers specify the bead impedance at a variety of current levels. In this case it is possible to make sure the ferrite bead maintains an adequate amount of impedance at the peak current the amplifier will see. If these specifications are not available, it is also possible to estimate the bead current handling capability by measuring the resonant frequency of the filter output at low power and at maximum power. A change of resonant frequency of less than fifty percent under this condition is desirable.

A high quality ceramic capacitor is also needed for the ferrite bead filter. A low ESR capacitor with good temperature and voltage characteristics will work best.

Additional EMC improvements may be obtained by adding snubber networks from each of the class D outputs to ground. Suggested values for a simple RC series snubber network would be  $10\ \Omega$  in series with a 330 pF capacitor although design of the snubber network is specific to every application and must be designed taking into account the parasitic reactance of the printed circuit board as well as the audio amp. Take care to evaluate the stress on the component in the snubber network especially if the amp is running at high PVCC. Also, make sure the layout of the snubber network is tight and returns directly to the PGND .

Efficiency: LC Filter Required With the Traditional Class-D Modulation Scheme

The main reason that the traditional class-D amplifier needs an output filter is that the switching waveform results in maximum current flow. This causes more loss in the load, which causes lower efficiency. The ripple current is large for the traditional modulation scheme, because the ripple current is proportional to voltage multiplied by the time at that voltage. The differential voltage swing is 2 × VCC, and the time at each voltage is half the period for the traditional modulation scheme. An ideal LC filter is needed to store the ripple current from each half cycle for the next half cycle, while any resistance causes power dissipation. The speaker is both resistive and reactive, whereas an LC filter is almost purely reactive.

The AT3110C modulation scheme has little loss in the load without a filter because the pulses are short and the change in voltage is VCC instead of 2 × VCC. As the output power increases, the pulses widen, making the ripple current larger. Ripple current could be filtered with an LC filter for increased efficiency, but for most applications the filter is not needed.

An LC filter with a cutoff frequency less than the class-D switching frequency allows the switching current to flow through the filter instead of the load. The filter has less resistance but higher impedance at the switching frequency than the speaker, which results in less power dissipation, therefore increasing efficiency.

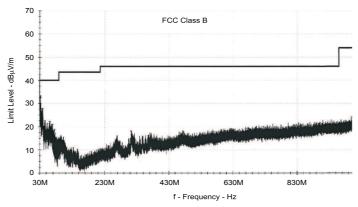


Figure 40. AT3110C EMC spectrum with FCC Class B Limits



# When to Use an Output Filter for EMI Suppression

The AT3110C has been tested with a simple ferrite bead filter for a variety of applications including long speaker wires up to 125 cm and high power. The AT3110C EVM passes FCC Class B specifications under these conditions using twisted speaker wires. The size and type of ferrite bead can be selected to meet application requirements. Also, the filter capacitor can be increased if necessary with some impact on efficiency.

There may be a few circuit instances where it is necessary to add a complete LC reconstruction filter. These circumstances might occur if there are nearby circuits which are sensitive to noise. In these cases a classic second order Butterworth filter similar to those shown in the figures below can be used.

Some systems have little power supply decoupling from the AC line but are also subject to line conducted interference (LCI) regulations. These include systems powered by "wall warts" and "power bricks." In these cases, it LC reconstruction filters can be the lowest cost means to pass LCI tests. Common mode chokes using low frequency ferrite material can also be effective at preventing line conducted interference.

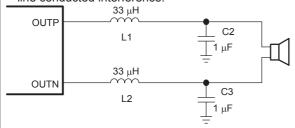


Figure 41. Typical LC Output Filter, Cutoff Frequency of 27 kHz, Speaker Impedance = 8  $\Omega$ 

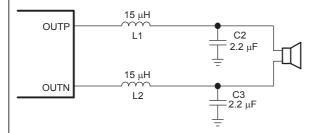


Figure 42. Typical LC Output Filter, Cutoff Frequency of 27 kHz, Speaker Impedance = 4  $\Omega$ 

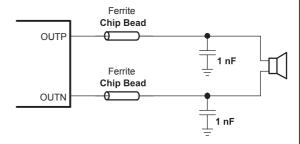
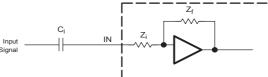


Figure 43. Typical Ferrite Chip Bead Filter (Chip Bead Example: )

#### **Input Resistance**

Changing the gain setting can vary the input resistance of the amplifier from its smallest value, 9 k $\Omega$  ±20%, to the largest value, 60 k $\Omega$  ±20%. As a result, if a single capacitor is used in the input high-pass filter, the -3 dB or cutoff frequency may change when changing gain steps.



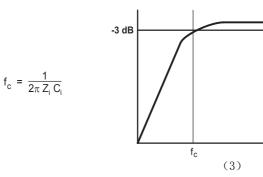
The -3-dB frequency can be calculated using Equation 2. Use the ZI values given in Table 1.

$$f = \frac{1}{2\pi Z_i C}$$

#### Input Capacitor, CI

In the typical application, an input capacitor (CI) is required to allow the amplifier to bias the input signal to the proper dc level for optimum operation. In this case, CI and the input impedance of the amplifier (ZI) form a highpass filter with the corner frequency determined in Equation 3.





The value of CI is important, as it directly affects the bass (low-frequency) performance of the circuit. Consider the example where ZI is 60 k $\Omega$  and the specification calls for a flat bass response down to 20 Hz. Equation 3 is reconfigured as Equation 4.

$$C_i = \frac{1}{2\pi Z_i f_c} \tag{4}$$

In this example, CI is 0.13 µF; so, one would likely choose a value of 0.15 µF as this value is commonly used. If the gain is known and is constant, use ZI from Table 1 to calculate CI. A further consideration for this capacitor is the leakage path from the input source through the input network (CI) and the feedback network to the load. This leakage current creates a dc offset voltage at the input to the amplifier that reduces useful headroom, especially in high gain applications. For this reason, a low-leakage tantalum or ceramic capacitor is the best choice. When polarized capacitors are used, the positive side of the capacitor should face the amplifier input in most applications as the dc level there is held at 3 V, which is likely higher than the source dc level. Note that it is important to confirm the capacitor polarity in the application. Additionally, lead-free solder can create dc offset voltages and it is important to ensure that boards are cleaned properly.

#### **Power Supply Decoupling, CS**

The AT3110C is a high-performance CMOS audio amplifier that requires adequate power supply decoupling to ensure that the output total harmonic distortion (THD) is as low as possible.

Power supply decoupling also prevents oscillations for long lead lengths between the amplifier and the speaker. Optimum decoupling is achieved by using a network of capacitors of different types that target specific types of noise on the power supply leads. For higher frequency transients due to parasitic circuit elements such as bond wire and copper trace inductances as well as lead frame capacitance, a good quality low equivalent-series-resistance (ESR) ceramic capacitor of value between 220 pF and 1000 pF works well. This capacitor should be placed as close to the device PVCC pins and system ground (either PGND pins or PowerPad) as possible. For mid-frequency noise due to filter resonances or PWM switching transients as well as digital hash on the line, another good quality capacitor typically 0.1  $\mu$ F to 1  $\mu$ F placed as close as possible to the device PVCC leads works best For filtering lower frequency noise signals, a larger aluminum electrolytic capacitor of 220 µF or greater placed near the audio power amplifier is recommended. The 220 µF capacitor also serves as a local storage capacitor for supplying current during large signal transients on the amplifier outputs. The PVCC terminals provide the power to the output transistors, so a 220 µF or larger capacitor should be placed on each PVCC terminal. A 10 µF capacitor on the AVCC terminal is adequate. Also, a small decoupling resistor between AVCC and PVCC can be used to keep high frequency class D noise from entering the linear input amplifiers.

#### **BSN and BSP Capacitors**

The full H-bridge output stages use only NMOS transistors. Therefore, they require bootstrap capacitors for the high side of each output to turn on correctly. A 0.22  $\mu\text{F}$  ceramic capacitor, rated for at least 25 V, must be connected from each output to its corresponding bootstrap input. Specifically, one 0.22  $\mu\text{F}$  capacitor must be connected from OUTPx to BSPx, and one 0.22  $\mu\text{F}$  capacitor must be connected from OUTPx to BSPx. (See the application circuit diagram in Figure 1.)

The bootstrap capacitors connected between the BSxx pins and corresponding output function as a floating power supply for the high-side N-channel



power MOSFET gate drive circuitry. During each high-side switching cycle, the bootstrap capacitors hold the gate-to-source voltage high enough to keep the high-side MOSFETs turned on.

#### **Differential Inputs**

The differential input stage of the amplifier cancels any noise that appears on both input lines of the channel. To use the AT3110C with a differential source, connect the positive lead of the audio source to the INP input and the negative lead from the audio source to the INN input. To use the AT3110C with a single-ended source, ac ground the INP or INN input through a capacitor equal in value to the input capacitor on INN or INP and apply the audio source to either input. In a single-ended input application, the unused input should be ac grounded at the audio source instead of at the device input for best performance. For good transient performance, the impedance seen at each of the two differential inputs should be the same.

The impedance seen at the inputs should be limited to an RC time constant of 1 ms or less if possible. This is to allow the input dc blocking capacitors to become completely charged during the 14 ms power-up time. If the input capacitors are not allowed to completely charge, there will be some additional sensitivity to component matching which can result in pop if the input components are not well matched.

#### **Using Low-ESR Capacitors**

Low-ESR capacitors are recommended throughout this application section. A real (as opposed to ideal) capacitor can be modeled simply as a resistor in series with an ideal capacitor. The voltage drop across this resistor minimizes the beneficial effects of the capacitor in the circuit. The lower the equivalent value of this resistance, the more the real capacitor behaves like an ideal capacitor.

#### Printed-Circuit Board (PCB) Layout

The AT3110C can be used with a small, inexpensive ferrite bead output filter for most applications. However, since the Class-D switching edges are fast, it is necessary to take care when planning the layout of the printed circuit board. The following suggestions will

help to meet EMC requirements.

- Decoupling capacitors—The high-frequency decoupling capacitors should be placed as close to the PVCC and AVCC terminals as possible. Large (220  $\mu\text{F}$  or greater) bulk power supply decoupling capacitors should be placed near the AT3110C on the PVCCL and PVCCR supplies. Local, high-frequency bypass capacitors should be placed as close to the PVCC pins as possible. These caps can be connected to the thermal pad directly for an excellent ground connection. Consider adding a small, good quality low ESR ceramic capacitor between 220 pF and 1000 pF and a larger mid-frequency cap of value between  $0.1\mu\text{F}$  and  $1\mu\text{F}$  also of good quality to the PVCC connections at each end of the chip.
- Keep the current loop from each of the outputs through the ferrite bead and the small filter cap and back to PGND as small and tight as possible. The size of this current loop determines its effectiveness as an antenna.
- Grounding—The AVCC (pin 7) decoupling capacitor should be grounded to analog ground (AGND). The PVCC decoupling capacitors should connect to PGND. Analog ground and power ground should be connected at the thermal pad, which should be used as a central ground connection or star ground for the AT3110C.
- Output filter—The ferrite EMI filter (Figure 43) should be placed as close to the output terminals as possible for the best EMI performance. The LC filter (Figure 41 and Figure 42) should be placed close to the outputs. The capacitors used in both the ferrite and LC filters should be grounded to power ground.
- Thermal Pad—The thermal pad must be soldered to the PCB for proper thermal performance and optimal reliability. The dimensions of the thermal pad and thermal land should be 6.46mm by 2.35mm. Seven rows of solid vias (three vias per row, 0,3302 mm or 13 mils diameter) should be equally spaced underneath the thermal land. The vias should connect to a solid copper plane, either on an internal layer or on the bottom layer of the PCB. The vias must be solid vias, not thermal relief or webbed vias.

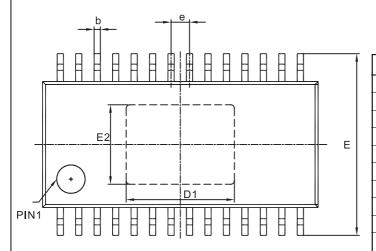
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# 25-W Filter-free Stereo Class-D Audio Power Amplifer

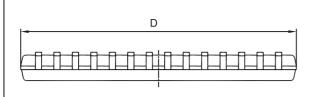
## **Package Information**

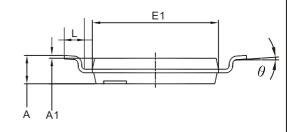
TSSOP28-EP



SYMBOL	MIN	NOM	МАХ
Α			1.200
A1	0.050		0.150
b	0.190	0.240	0.300
- 4	4 000	4 400	4 500

A1	0.050		0.150
b	0.190	0.240	0.300
E1	4.300	4.400	4.500
D	10.262		10.414
D1	5.640	5.760	5.940
E	6.250	6.450	6.550
E2	2.740		3.050
е	0.650		
L			1.000
θ (° C)	0		8





#### Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Package body sizes exclude mold flash and gate burrs.